ABSTRACT OF THE DISCLOSURE

A semiconductor device of the present invention has two inner inner leads to be bonded with inner-side bump electrodes each placed at a position which is a relatively large distance apart from the edge of a semiconductor chip, between outer-side bump electrodes each placed at a position which is a relatively small distance apart from the edge of the semiconductor chip. At least one of the inner inner leads is bent in accordance with a bonding position with the inner-side bump electrode.